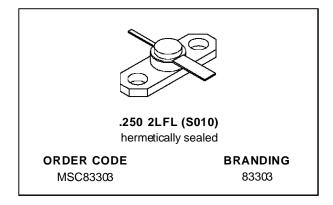
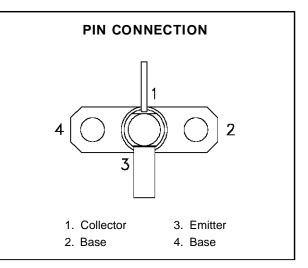


MSC83303

RF & MICROWAVE TRANSISTORS GENERAL PURPOSE AMPLIFIER APPLICATIONS

- REFRACTORY/GOLD METALLIZATION
- EMITTER BALLASTED
- VSWR CAPABILITY ∞:1 @ RATED CONDITIONS
- HERMETIC STRIPAC[®] PACKAGE
- $P_{OUT} = 3.0$ W MIN. WITH 7.0 dB GAIN @ 3.0 GHz





DESCRIPTION

The MSC83303 is a common base hermetically sealed silicon NPN microwave power transistor utilizing an overlay, emitter site ballasted geometry with a refractory/gold metallization system. This device is capable of withstanding an infinite load VSWR at any phase angle under rated conditions. The MSC83303 is designed for Class C amplifier/oscillator applications in the 1.0 - 3.0 GHz frequency range.

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$)		
	Symbol	Parameter

Symbol	Parameter	Value	Unit
PDISS	Power Dissipation* $(T_C \le 50^{\circ}C)$	10.0	W
lc	Device Current*	540	mA
V _{CC}	Collector-Supply Voltage*	30	V
TJ	Junction Temperature	200	°C
T _{STG}	Storage Temperature	– 65 to +200	°C

THERMAL DATA

RTH(j-c)	Junction-Case Thermal Resistance*	12	°C/W
*Applies only to rated R	F amplifier operation		

MSC83303

ELECTRICAL SPECIFICATIONS $(T_{case} = 25^{\circ}C)$

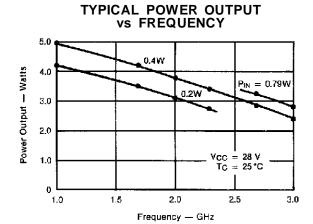
STATIC

Symbol	Test Conditions	Value			Unit		
Symbol		Test conditions		Min.	Тур.	Max.	Unit
BV _{CBO}	$I_C = 1 \text{ mA}$	$I_E = 0 mA$		45	_		V
BVEBO	$I_E = 1 \text{ mA}$	$I_C = 0 \text{ mA}$		3.5	—		V
BVCER	$I_C = 5 \text{ mA}$	$R_{BE} = 10 \ \Omega$		45	_	_	V
Ісво	V _{CB} = 28 V			_	_	0.5	mA
h _{FE}	$V_{CE} = 5 V$	$I_C = 200 \text{ mA}$		30		300	_

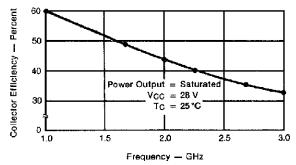
DYNAMIC

Symbol	Test Conditions				Value		
Symbol				Min.	Тур.	Max.	Unit
Роит	f = 3.0 GHz	$P_{IN}=0.79\ W$	$V_{CC} = 28 V$	2.5	2.8	—	W
ηc	f = 3.0 GHz	$P_{IN}=0.79\ W$	$V_{CC} = 28 V$	30	33	—	%
PG	f = 3.0 GHz	$P_{IN}=0.79\ W$	$V_{CC} = 28 V$	5.0	5.5	—	dB
Сов	f = 1 MHz	$V_{CB} = 28 V$		_		5	pF

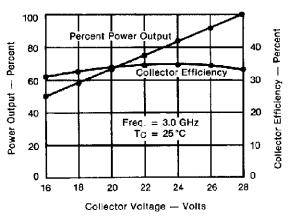
TYPICAL PERFORMANCE





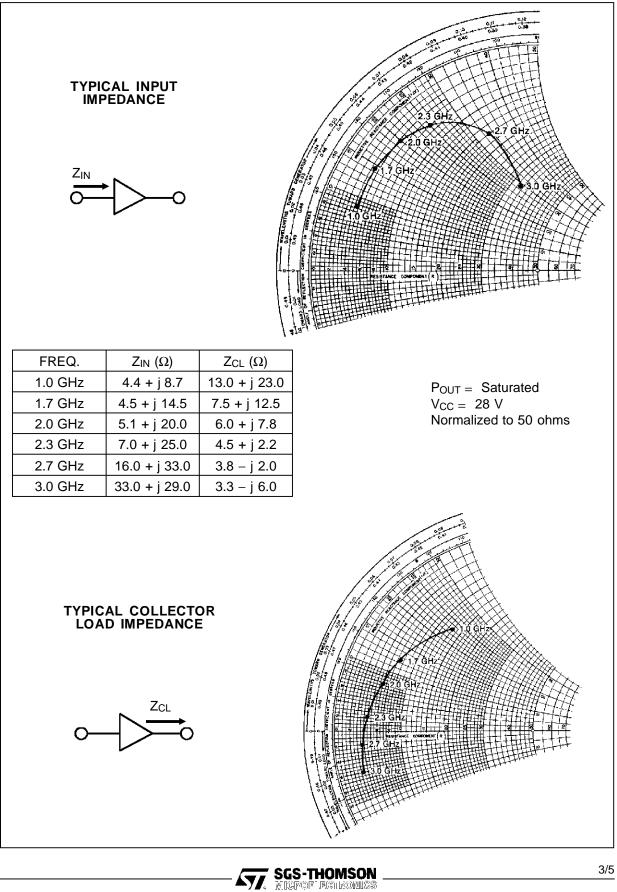


PERCENT POWER OUTPUT & COLLECTOR EFFICIENCY vs COLLECTOR VOLTAGE



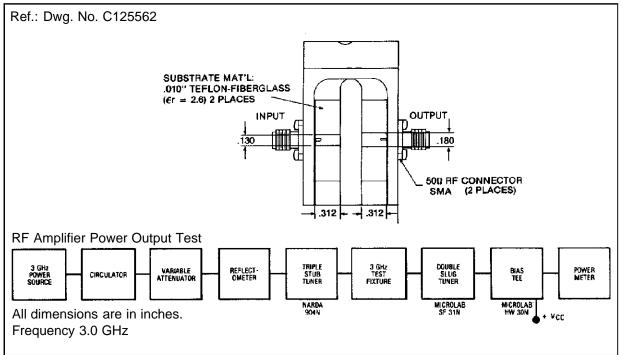


IMPEDANCE DATA



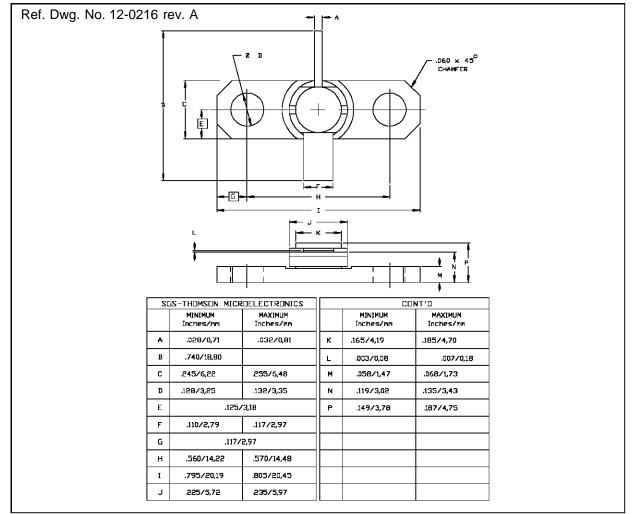
S/.

TEST CIRCUIT





PACKAGE MECHANICAL DATA



Information furnished is believed to be accurate and reliable. However, SGS-THOMSON Microelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of SGS-THOMSON Microelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. SGS-THOMSON Microelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of SGS-THOMSON Microelectronics.

©1994 SGS-THOMSON Microelectronics - All Rights Reserved

SGS-THOMSON Microelectronics GROUP OF COMPANIES Australia - Brazil - France - Germany - Hong Kong - Italy - Japan - Korea - Malaysia - Malta - Morocco - The Netherlands -Singapore - Spain - Sweden - Switzerland - Taiwan - Thailand - United Kingdom - U.S.A.

